Data sheet acquired from Harris Semiconductor SCHS210B

August 1997 - Revised March 2002

High Speed CMOS Logic Triple 3-Input OR Gate

Features

- · Buffered Inputs
- Typical Propagation Delay: 8ns at V_{CC} = 5V, C_L = 15pF, T_A = 25°C
- Fanout (Over Temperature Range)

 - - -
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
 - 2V to 6V Operation
 - High Noise Immunity: N_{IL} = 30%, N_{IH} = 30% of V_{CC} at V_{CC} = 5V
- HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility,
 V_{IL}= 0.8V (Max), V_{IH} = 2V (Min)
 - CMOS Input Compatibility, I $_I \leq 1 \mu A$ at $V_{OL},\,V_{OH}$

Description

The 'HC4075 and 'HCT4075 logic gates utilize silicon-gate CMOS technology to achieve operating speeds similar to LSTTL gates with the low power consumption of standard CMOS integrated circuits. All devices have the ability to drive 10 LSTTL loads. The HCT logic family is functionally pin compatible with the standard LS logic family.

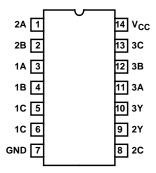
Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC4075F3A	-55 to 125	14 Ld CERDIP
CD74HC4075E	-55 to 125	14 Ld PDIP
CD74HC4075M	-55 to 125	14 Ld SOIC
CD74HC4075NSR	-55 to 125	14 Ld SOP
CD54HCT4075F3A	-55 to 125	14 Ld CERDIP
CD74HCT4075E	-55 to 125	14 Ld PDIP
CD74HCT4075M	-55 to 125	14 Ld SOIC

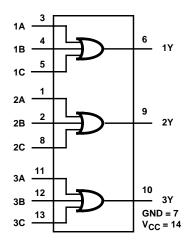
NOTE: When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.

Pinout

CD54HC4075, CD54HCT4075 (CERDIP) CD74HC4075 (PDIP, SOIC, SOP) CD74HCT4075 (PDIP, SOIC) TOP VIEW



Functional Diagram

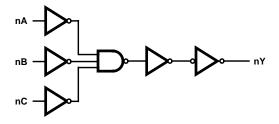


TRUTH TABLE

	OUTPUT		
nA	nB	nY	
L	L	L	L
Н	Х	X	Н
Х	Н	X	Н
Х	Х	Н	Н

NOTE: H = High Voltage Level, L = Low Voltage Level, X = Irrelevant

Logic Diagram



Absolute Maximum Ratings

DC Supply Voltage, V _{CC} 0.5V to 7V
DC Input Diode Current, I _{IK}
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V \dots \pm 20 \text{mA}$
DC Output Diode Current, I _{OK}
For V _O < -0.5V or V _O > V _{CC} + 0.5V±20mA
DC Output Source or Sink Current per Output Pin, IO
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$
DC V _{CC} or Ground Current, I _{CC or} I _{GND} ±50mA

Thermal Information

Package Thermal Impedance, θ _{JA} (see Note 1):
PDIP Package
SOIC Package
SOP Package 76°C/W
Maximum Junction Temperature (Hermetic Package or Die) . 175°C
Maximum Junction Temperature (Plastic Package) 150°C
Maximum Storage Temperature Range65°C to 150°C
Maximum Lead Temperature (Soldering 10s)300°C
(SOIC - Lead Tips Only)

Operating Conditions

Temperature Range (T _A)55°C to 125°C
Supply Voltage Range, V _{CC}
HC Types2V to 6V
HCT Types
DC Input or Output Voltage, V _I , V _O
Input Rise and Fall Time
2V
4.5V 500ns (Max)
6V

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

		TEST CONDITIONS		v _{cc}	25°C			-40°C TO 85°C		-55°C TO 125°C		
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES					-	-		-				
High Level Input	V _{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V
Voltage				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input	V _{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V
Voltage				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output	VoH	V _{IH} or V _{IL}	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
Voltage CMOS Loads			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
OWOO LOUGS			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output	7		-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Voltage TTL Loads			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output	V _{OL}	V _{OL} V _{IH} or V _{IL}	0.02	2	-	-	0.1	-	0.1	-	0.1	V
Voltage CMOS Loads			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
OWIGO Educa			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output	1		4	4.5	-	-	0.26	-	0.33	-	0.4	V
Voltage TTL Loads			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	lı	V _{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	μΑ
Quiescent Device Current	Icc	V _{CC} or GND	0	6	-	-	2	-	20	-	40	μΑ

DC Electrical Specifications (Continued)

		TES CONDI		v _{cc}	25°C			-40°C TO 85°C		-55°C TO 125°C		
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HCT TYPES												
High Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	ı	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V _{OH}	V _{IH} or V _{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	=	0.33	-	0.4	V
Input Leakage Current	lį	V _{CC} and GND	0	5.5	-		±0.1	-	±1	-	±1	μА
Quiescent Device Current	Icc	V _{CC} or GND	0	5.5	-	-	2	-	20	-	40	μА
Additional Quiescent Device Current Per Input Pin: 1 Unit Load (Note)	Δl _{CC}	V _{CC} -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μА

NOTE: For dual-supply systems theoretical worst case ($V_I = 2.4V$, $V_{CC} = 5.5V$) specification is 1.8mA.

HCT Input Loading Table

INPUT	UNIT LOADS
All	1.6

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Table, e.g. 360µA max at 25°C.

Switching Specifications Input t_r , t_f = 6ns

		TEST		25°C			-40°C TO 85°C		-55°C TO 125°C		
PARAMETER	SYMBOL	CONDITIONS	V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
HC TYPES					-	-					
Propagation Delay, Input to Output (Figure 1)	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	100	-	125	-	150	ns
			4.5	-	-	20	-	25	-	30	ns
			6	-	-	17	-	21	-	26	ns
		C _L = 15pF	5	-	8	-	-	-	-	-	ns
Transition Times (Figure 1)	t _{TLH} , t _{THL}	C _L = 50pF	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Input Capacitance	C _{IN}	-	-	-	_	10	-	10	-	10	pF

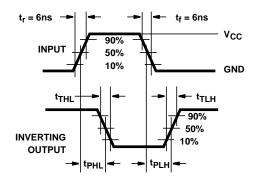
Switching Specifications Input t_r , $t_f = 6ns$ (Continued)

		TEST		25°C			-40°C TO 85°C		-55°C TO 125°C		
PARAMETER	SYMBOL	CONDITIONS	V _{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
Power Dissipation Capacitance (Notes 2, 3)	C _{PD}	-	5	-	26	-	-	-	-	-	pF
HCT TYPES											
Propagation Delay, Input to	t _{PLH} , t _{PHL}	C _L = 50pF	4.5	-	-	24	-	30	-	36	ns
Output (Figure 2)		C _L = 15pF	5	-	9	-	-	-	-	-	ns
Transition Times (Figure 2)	t _{TLH} , t _{THL}	C _L = 50pF	4.5	-	-	15	-	19	-	22	ns
Input Capacitance	C _{IN}	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 2, 3)	C _{PD}	-	5	-	28	-	-	-	-	-	pF

NOTES:

- 2. $C_{\mbox{\scriptsize PD}}$ is used to determine the dynamic power consumption, per gate.
- 3. $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$ where f_i = Input Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.

Test Circuits and Waveforms



 $t_{r} = 6 \text{ns} \longrightarrow t_{f} = 6 \text{ns}$ 1.3V 0.3V t_{THL} 0.3V 0.3V 0.3V 0.3V 1.3V 0.3V 1.3V 0.13V 1.3V 0.13V 1.3V 1

FIGURE 1. HC AND HCU TRANSITION TIMES AND PROPAGA-TION DELAY TIMES, COMBINATION LOGIC

FIGURE 2. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

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